



CEP85A3/CEB85A3

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

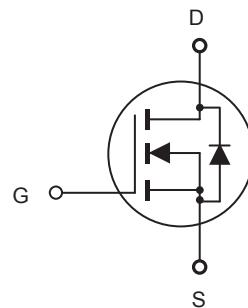
- 25V, 90A, $R_{DS(ON)} = 6\text{m}\Omega$ @ $V_{GS} = 10\text{V}$.
 $R_{DS(ON)} = 9\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- TO-263 & TO-220 package.



CEB SERIES
TO-263(DD-PAK)



CEP SERIES
TO-220



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	25	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	90	A
Drain Current-Pulsed ^a	I_{DM}	360	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	P_D	89 0.71	W W/ $^\circ\text{C}$
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.4	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	25			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 30\text{A}$		5.0	6.0	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 24\text{A}$		7.5	9.0	$\text{m}\Omega$
Dynamic Characteristics^c						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		2320		pF
Output Capacitance	C_{oss}			335		pF
Reverse Transfer Capacitance	C_{rss}			170		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 15\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		16	30	ns
Turn-On Rise Time	t_r			5	10	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			75	90	ns
Turn-On Fall Time	t_f			9	20	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 15\text{V}, I_D = 16\text{A}, V_{\text{GS}} = 5\text{V}$		17	22	nC
Gate-Source Charge	Q_{gs}			6		nC
Gate-Drain Charge	Q_{gd}			5		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				20	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 20\text{A}$			1.3	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- c.Guaranteed by design, not subject to production testing.

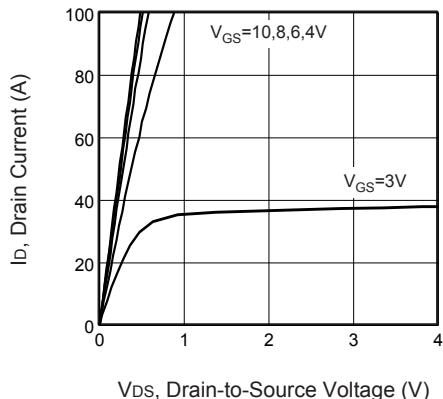


Figure 1. Output Characteristics

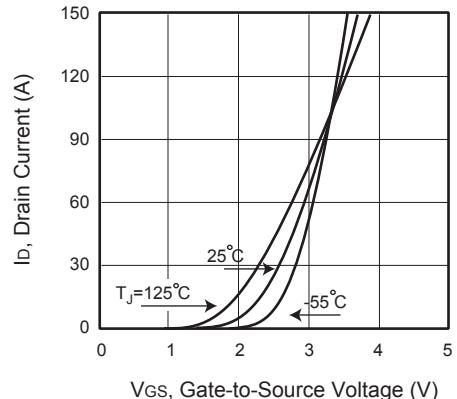


Figure 2. Transfer Characteristics

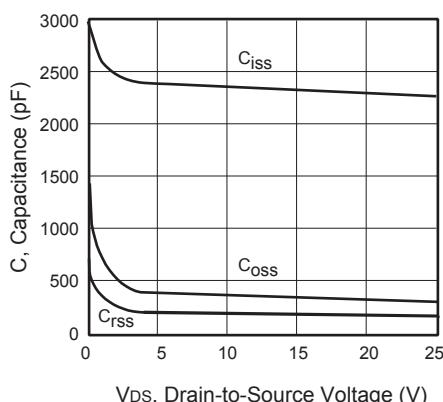


Figure 3. Capacitance

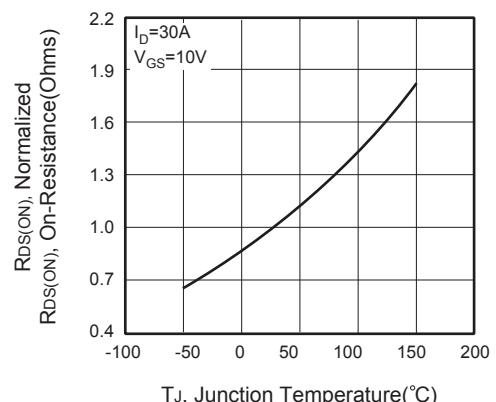


Figure 4. On-Resistance Variation with Temperature

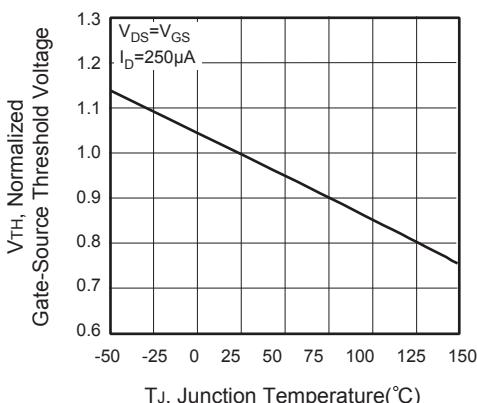


Figure 5. Gate Threshold Variation with Temperature

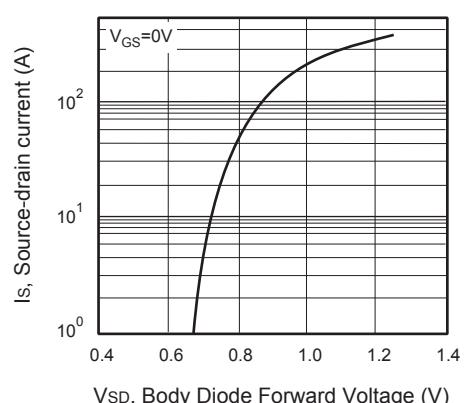


Figure 6. Body Diode Forward Voltage Variation with Source Current

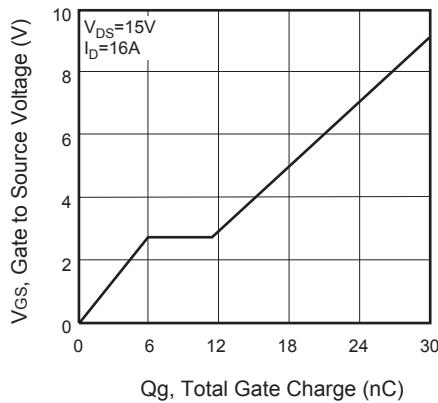
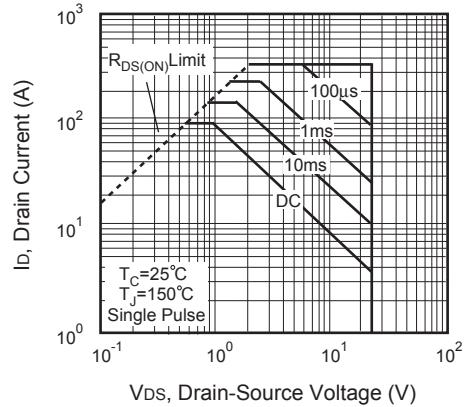


Figure 7. Gate Charge



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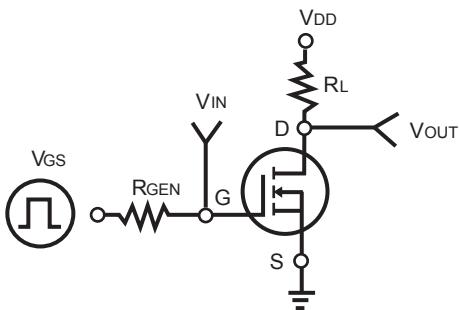


Figure 9. Switching Test Circuit

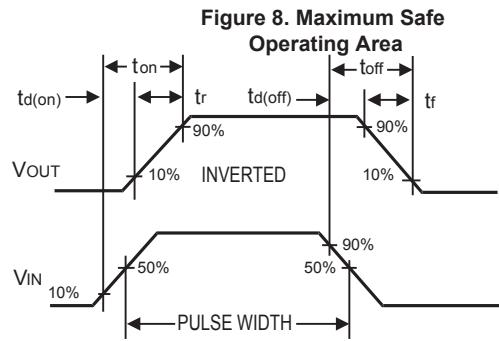


Figure 10. Switching Waveforms

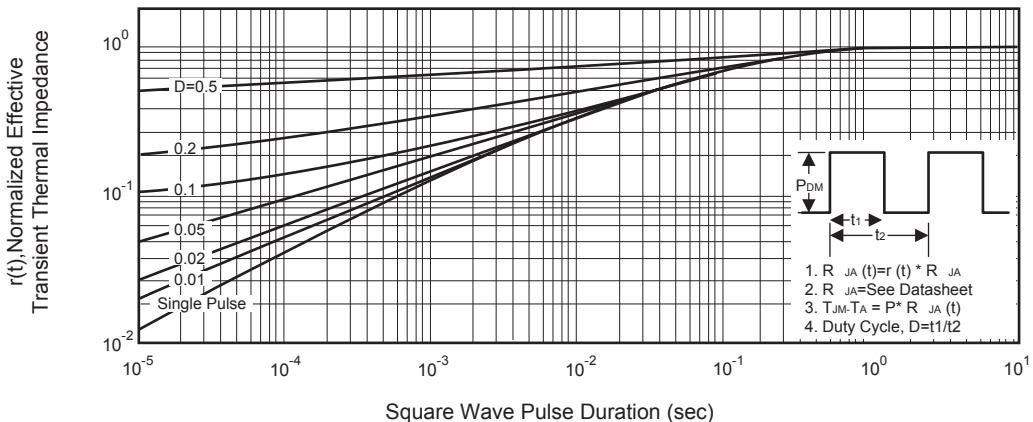


Figure 11. Normalized Thermal Transient Impedance Curve